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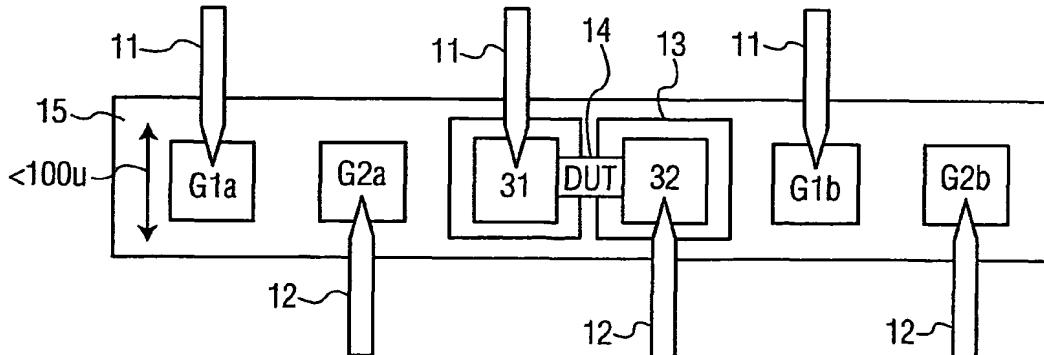
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[Continued on next page]

(54) Title: A GROUND-SIGNAL-GROUND (GSG) TEST STRUCTURE



(57) Abstract: A ground-signal-ground (GSG) test structure for production measurement of RF device performance in integrated circuits comprises one pair of signal pads (S1, S2) and two pairs of ground pads (G1a, G1b; G2a, G2b). All the six pads (G1a, G2a, S1, S2, G1b, G2b) are arranged linearly, whereby the width of the structure is small enough for the structure to be placed in a narrow saw lane of a wafer.

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